

客户图

NOTES:

1.MATERIAL

- 1.1 HOUSING: Polyester(PA6T),UL94 V-0
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 3.0 AMP,AC/DC
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 125V,AC/Minute
- 2.3 CONTACT RESISTANCE: 100mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000 mΩ Min
- 2.5 Operation Temperature:-40°C to +105°C

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

61F9-JX-XXX-SX-155-C 01

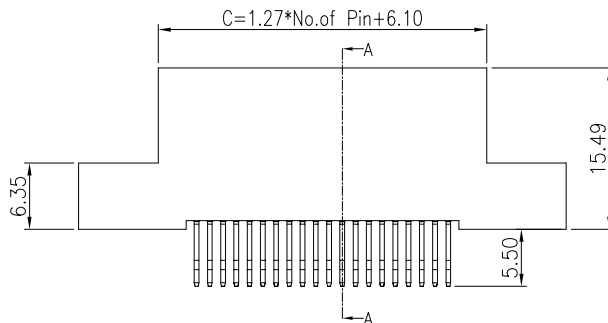
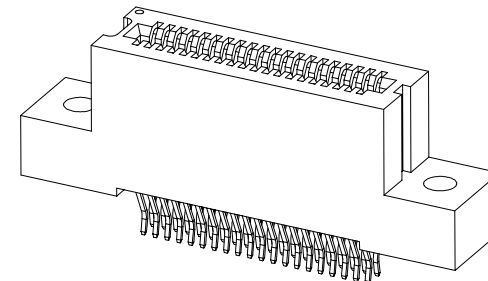
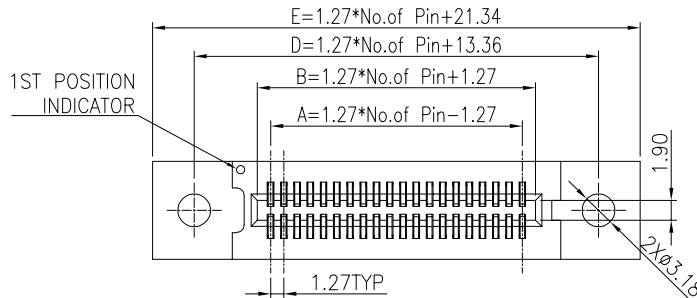
J1=带耳
J2=无耳

流水码:
01-99

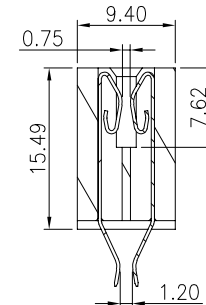
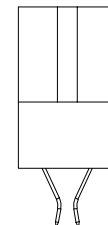
Pin数码:
010=2*5PIN
200=2*100PIN

端子电镀:
S0=Gold Tin
S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

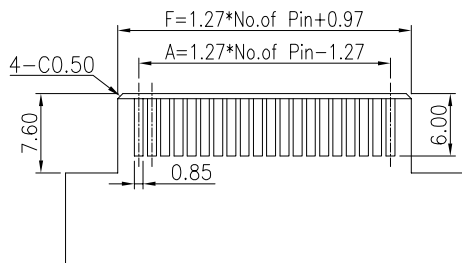
塑胶高度:
155=15.49mm
包装方式:
R=REEL
C=TRAY



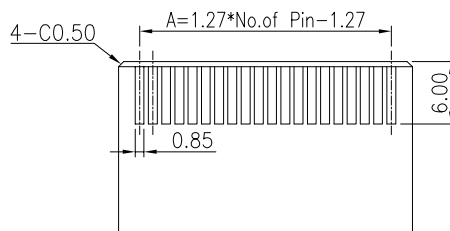
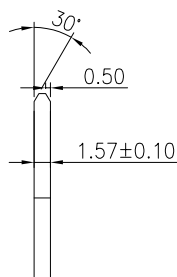
61F9-J1-XXX-SX-155-C 01



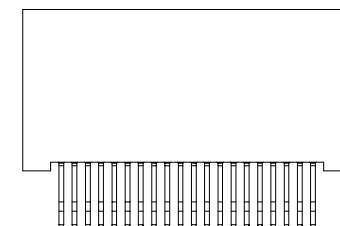
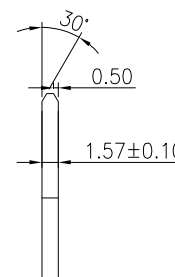
SECTION A-A



RECOMMENDED PLUG-PCB LAYOUT
TOLERANCE ±0.05



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCE±0.05



61F9-J2-XXX-SX-155-C 01

					OPERATION		DRAW		Mr.Zeng		2025.12.10		SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X	±0.40	DESIGN		Jensen		2025.12.10						
					X.XX	±0.25	CHECK		Jack		2025.12.10						
					X.XXX	±0.15	APPROVE		Andy		2025.12.10						
					Angle	±3'							SIZE	A4	PART NO.	61F9-JX-XXX-SX-155-C 01	
A0			NEW	_____	_____									SHEET	1/1	TITLE:	61F9_1.27mm 金手指夹板
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1846		

客户图

NOTES:

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- 2.3 CONTACT RESISTANCE: 100mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000 mΩ Min
- 2.5 Operation Temperature:-40°C to +105°C

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

61F9-MX-XXX-SX-155-C 01

M1=带耳
M2=无耳

流水码:
01-99

Pin数码:

010=2*5PIN
200=2*100PIN

端子电镀:

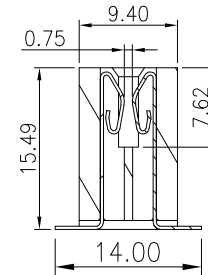
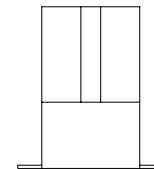
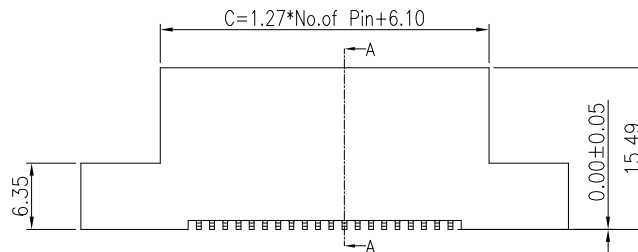
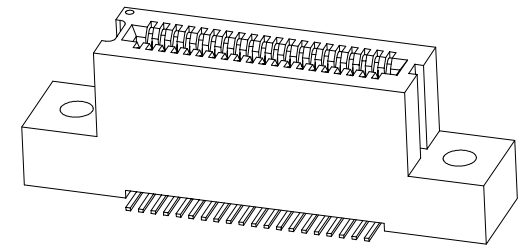
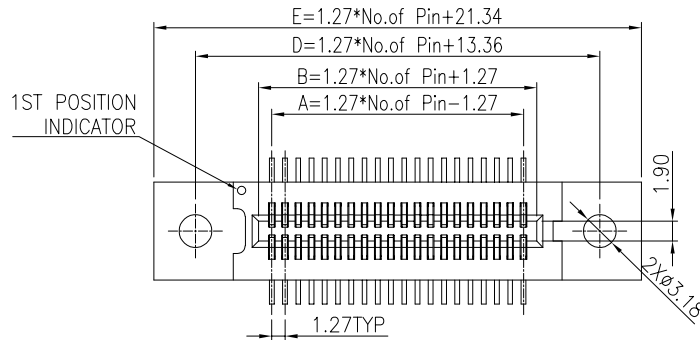
S0=Gold Tin
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S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

塑胶高度:

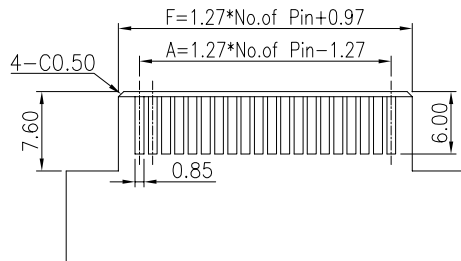
155=15.49mm

包装方式:

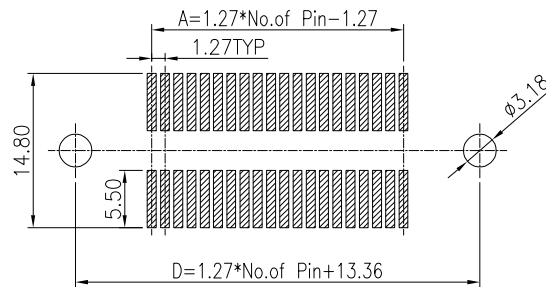
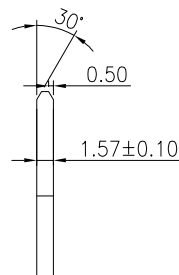
R=REEL
C=TRAY



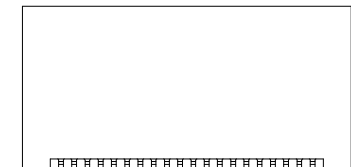
SECTION A-A



RECOMMENDED PLUG-PCB LAYOUT
TOLERANCE ±0.05



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCE±0.05



61F9-M2-XXX-SX-155-C 01

					OPERATION		DRAW		Mr.Zeng		2025.12.10		SOLEPiN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.							
					X.X	±0.40	DESIGN		Jensen		2025.12.10									
					X.XX	±0.25	CHECK		Jack		2025.12.10						SIZE	A4	PART NO.	61F9-MX-XXX-SX-155-C 01
					X.XXX	±0.15	APPROVE		Andy		2025.12.10						SHEET	1/1	TITLE:	61F9_1.27mm 金手指SMT
AO		NEW		——	——	Angle	±3°													
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1885				

1	2	3	4	5	6	7	8	9	10
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客户图

NOTES:

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- 1.1 HOUSING: Polyester(PA6T),UL94 V-0
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- 2.5 Operation Temperature:-40°C to +105°C

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

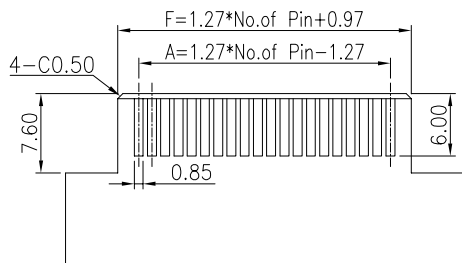
4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

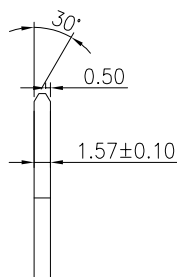
61F9-R2-XXX-SX-XXX-C 01

R1=带耳 R2=无耳 流水码: 01-99

Pin数码: 010=2*5PIN 200=2*100PIN
端子电镀: S0=Gold Tin S1=1u" Gold/Tin S2=3u" Gold/Tin S3=5u" Gold/Tin S4=10u" Gold/Tin S5=15u" Gold/Tin S6=30u" Gold/Tin
塑胶高度: 094=9.40mm 155=15.49mm
包装方式: R=REEL C=TRAY

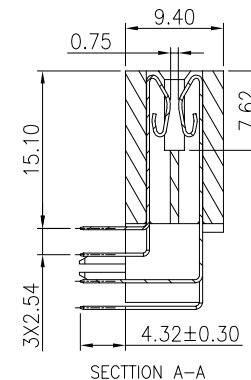
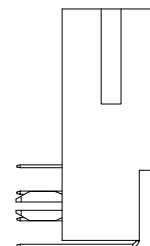
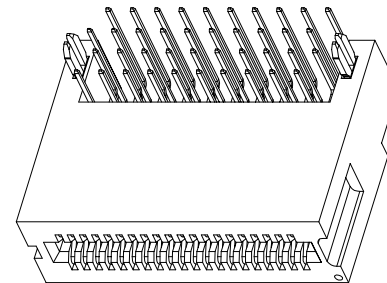
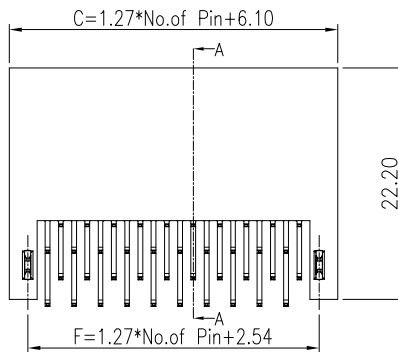
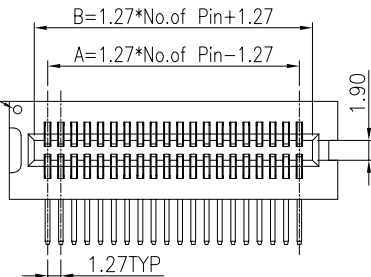


RECOMMENDED PLUG-PCB LAYOUT
TOLERANCE ±0.05



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE ±0.05

1ST POSITION
INDICATOR



					OPERATION		DRAW		Mr.Zeng		2025.12.10		SOLEPiN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.							
					X.X	±0.40	DESIGN		Jensen		2025.12.10									
					X.XX	±0.25	CHECK		Jack		2025.12.10						SIZE	A4	PART NO.	61F9-R2-XXX-SX-XXX-C 01
					X.XXX	±0.15	APPROVE				2025.12.10						SHEET	1/1	TITLE:	61F9_1.27mm 金手指 90° DIP无耳
A0		NEW		_____	_____	Angle	±3°			Andy		2025.12.10								
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1887					